

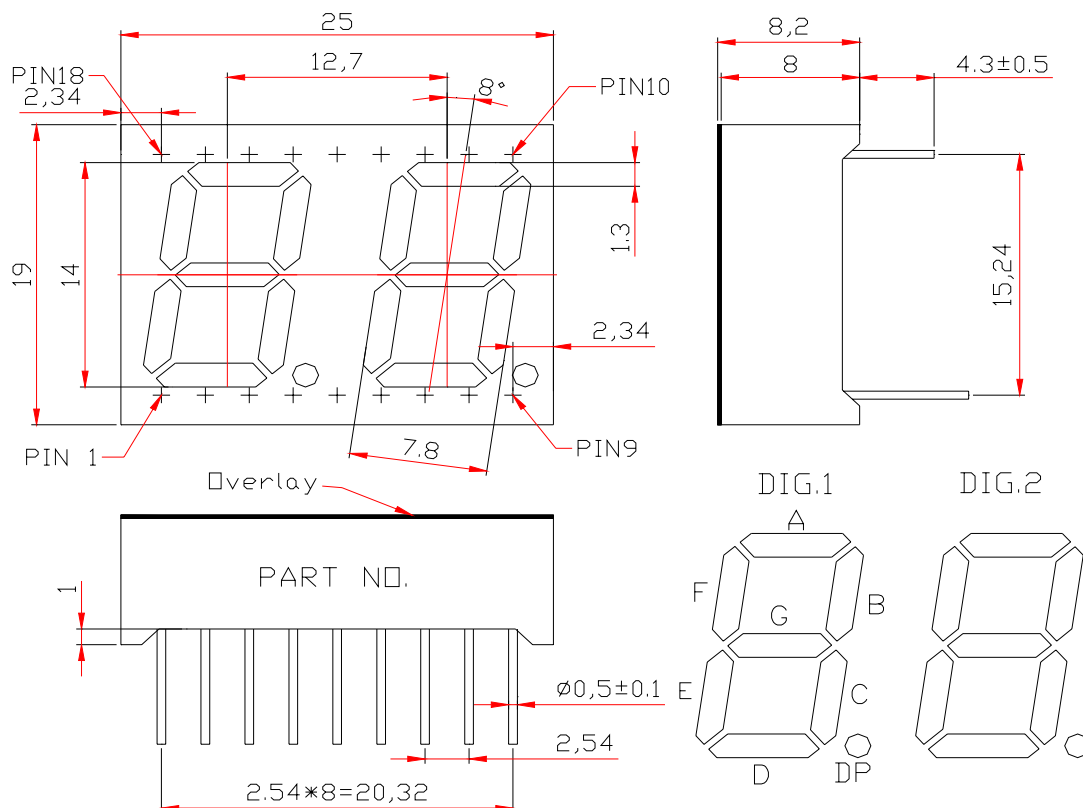
WCN2-0456BW-C11-F**SPECIFICATION**

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2016-10-6	Athena	William	
REVISION RECORD			



REVISION: A0

Outer Dimension:



Notes: Unless otherwise stated, the tolerance is $\pm 0.25\text{mm}$.

Circuit Diagram

Overlay:



Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Anode 1E	7	Anode 2G	13	Common Cathode Dig2
2	Anode 1D	8	Anode 2C	14	Common Cathode Dig1
3	Anode 1C	9	Anode DP2	15	Anode 1B
4	Anode DP1	10	Anode 2B	16	Anode 1A
5	Anode 2E	11	Anode 2A	17	Anode 1G
6	Anode 2D	12	Anode 2F	18	Anode 1F

WCN Opto Group Co., Limited

■ Features:

- High Reliability
- Color: White
- Low Power Requirement
- Easy Assembly

■ Description:

- Dual Digit Display
- Digit Height: 14.2 mm (0.56")
- Black Face and Yellow Segment with Black Overlay

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment	P _d	—	White	90	mW
Forward Current Per Segment	I _F	—	White	25	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	White	100	mA
Reverse Voltage Per Segment	V _R	—	White	5	V
Operating Temperature Range	T _{opr}	—	—	-35~+85	°C
Storage Temperature Range	T _{stg}	—	—	-35~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Segment	—	3.20	3.60	V
Reverse Current	I _R	V _R =5V	Per Segment	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Segment	10501	16500	26000	μcd
CIE Coordinate	X	I _F =20mA	Per Segment	—	0.2311	—	
	Y				0.2351		
Spectral Line Half Width	△λ	I _F =20mA	Per Segment	—	20	—	nm
Luminous Intensity Matching Ratio (Segment to Segment)	I _{v-m}	I _F =10mA	—	—	—	1.2:1	

■ Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)

Rank	Symbol	Condition	Min	Max	Unit
Q	Q	I _F =10mA	10501	12800	μcd
R	R	I _F =10mA	12801	15250	μcd
S	S	I _F =10mA	15251	18000	μcd
T	T	I _F =10mA	18001	21500	μcd
U	U	I _F =10mA	21501	26000	μcd

■ Soldering Conditions: Soldering Temp. ≤+260°C, Soldering Time. ≤3sec.
(at 2mm Distance from The Case of Reflector Edge)

LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T_a = UNDER ROOM TEMPERATURE $I_F = I_F \text{ max}$
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY $T_a = 65 \pm 5^\circ\text{C}$ RH=90~95%RH TEST TIME=240 $\pm$ 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE $T_a = 85 \pm 5^\circ\text{C}$ (COB: $T_a = 65 \pm 5^\circ\text{C}$) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE $T_a = -35 \pm 5^\circ\text{C}$ TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION $85^\circ\text{C} \sim 25^\circ\text{C} \sim -35^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES $85 \pm 5^\circ\text{C} \sim -35 \pm 5^\circ\text{C}$ 10min 10min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE $T_{\text{SOL}}=230 \pm 5^\circ\text{C}$ DWELL TIME=5 $\pm$ 1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING $T_{\text{SOL}}=260 \pm 5^\circ\text{C}$ DWELL TIME=10 $\pm$ 1sec.

Packing method A:

102 pcs / Red Expandable Polyethylene.

610 pcs / Box(360*175*130mm).

3660 pcs / Carton(550*380*280mm).

Packing method B:

20 pcs / IC Tube.(520*24.3*19.3)

840 pcs / Box(537*175*125mm).

3360 pcs / Carton(550*380*280mm).